



Connectors > Socket Connectors > Memory Sockets > SO DIMM Sockets > DDR2 SO DIMM Sockets



DRAM Type: Double Data Rate (DDR)  
Stack Height: 5.2 mm [ .205 in ]  
Module Orientation: Right Angle  
Number of Positions: 200  
Centerline (Pitch): .6 mm [ .024 in ]

[All DDR2 SO DIMM Sockets \(30\)](#)

Features

Product Type Features

|                                   |                        |
|-----------------------------------|------------------------|
| Connector System                  | Cable-to-Board         |
| Connector & Contact Terminates To | Printed Circuit Board  |
| DRAM Type                         | Double Data Rate (DDR) |

Configuration Features

|                     |             |
|---------------------|-------------|
| Number of Bays      | 2           |
| Number of Keys      | 1           |
| Number of Rows      | 2           |
| Module Orientation  | Right Angle |
| Number of Positions | 200         |

Electrical Characteristics

|              |       |
|--------------|-------|
| DRAM Voltage | 2.5 V |
|--------------|-------|

Signal Characteristics

|  |  |
|--|--|
|  |  |
|--|--|



|               |       |
|---------------|-------|
| SGRAM Voltage | 2.5 V |
|---------------|-------|

Body Features

|                        |                 |
|------------------------|-----------------|
| Ejector Location       | Both Ends       |
| Latch Material         | Stainless Steel |
| Latch Plating Material | Tin             |
| Module Key Type        | SGRAM           |
| Ejector Type           | Locking         |
| Connector Profile      | Standard        |

Contact Features

|                                               |              |
|-----------------------------------------------|--------------|
| Memory Socket Type                            | Memory Card  |
| PCB Contact Termination Area Plating Material | Gold Flash   |
| Contact Base Material                         | Copper Alloy |
| Contact Current Rating (Max)                  | .5 A         |
| Contact Mating Area Plating Material          | Gold Flash   |

Termination Features

|                                             |               |
|---------------------------------------------|---------------|
| Insertion Style                             | Cam-In        |
| Termination Method to Printed Circuit Board | Surface Mount |

Mechanical Attachment

|                          |                 |
|--------------------------|-----------------|
| Mating Alignment Type    | Standard Keying |
| PCB Mount Retention      | With            |
| PCB Mount Retention Type | Solder Peg      |
| Connector Mounting Type  | Board Mount     |

Housing Features

|                    |                                |
|--------------------|--------------------------------|
| Housing Material   | High Temperature Thermoplastic |
| Housing Color      | Black                          |
| Centerline (Pitch) | .6 mm[.024 in]                 |

Dimensions

|                    |                 |
|--------------------|-----------------|
| Stack Height       | 5.2 mm[.205 in] |
| Row-to-Row Spacing | 6.2 mm[.244 in] |

Usage Conditions

|                             |                           |
|-----------------------------|---------------------------|
| Operating Temperature Range | -55 – 85 °C[-67 – 185 °F] |
|-----------------------------|---------------------------|

Operation/Application



|                     |       |
|---------------------|-------|
| Circuit Application | Power |
|---------------------|-------|

Industry Standards

|                        |          |
|------------------------|----------|
| UL Flammability Rating | UL 94V-0 |
|------------------------|----------|

Packaging Features

|                    |             |
|--------------------|-------------|
| Packaging Quantity | 150         |
| Packaging Method   | Tape & Reel |

Product Compliance

For compliance documentation, visit the product page on TE.com>

|                                               |                                                                                                                                |
|-----------------------------------------------|--------------------------------------------------------------------------------------------------------------------------------|
| EU RoHS Directive 2011/65/EU                  | Compliant                                                                                                                      |
| EU ELV Directive 2000/53/EC                   | Compliant                                                                                                                      |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold                                                                                        |
| EU REACH Regulation (EC) No. 1907/2006        | Current ECHA Candidate List: JUNE 2024 (241)<br>Candidate List Declared Against: JAN 2023 (233)<br>Does not contain REACH SVHC |
| Halogen Content                               | Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free                                            |
| Solder Process Capability                     | Reflow solder capable to 260°C                                                                                                 |

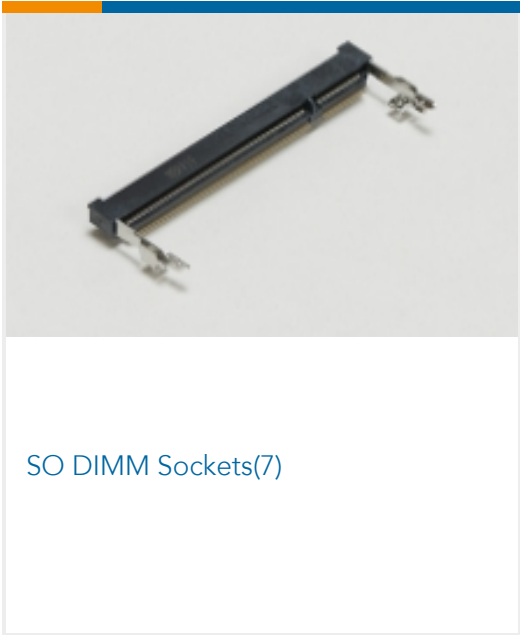
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

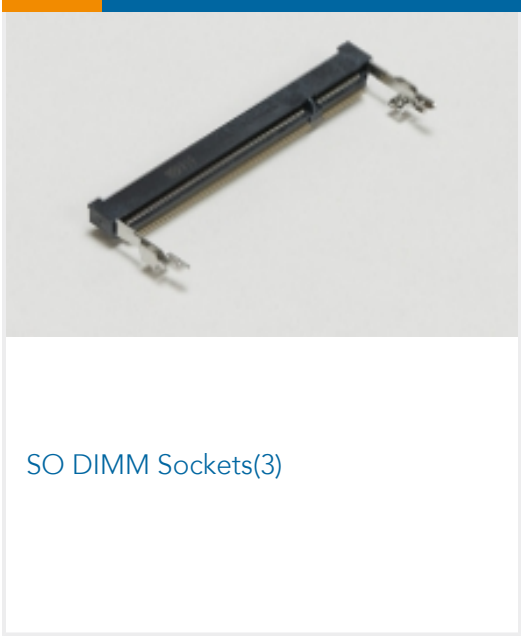
Compatible Parts



Also in the Series | **DDR SODIMM**

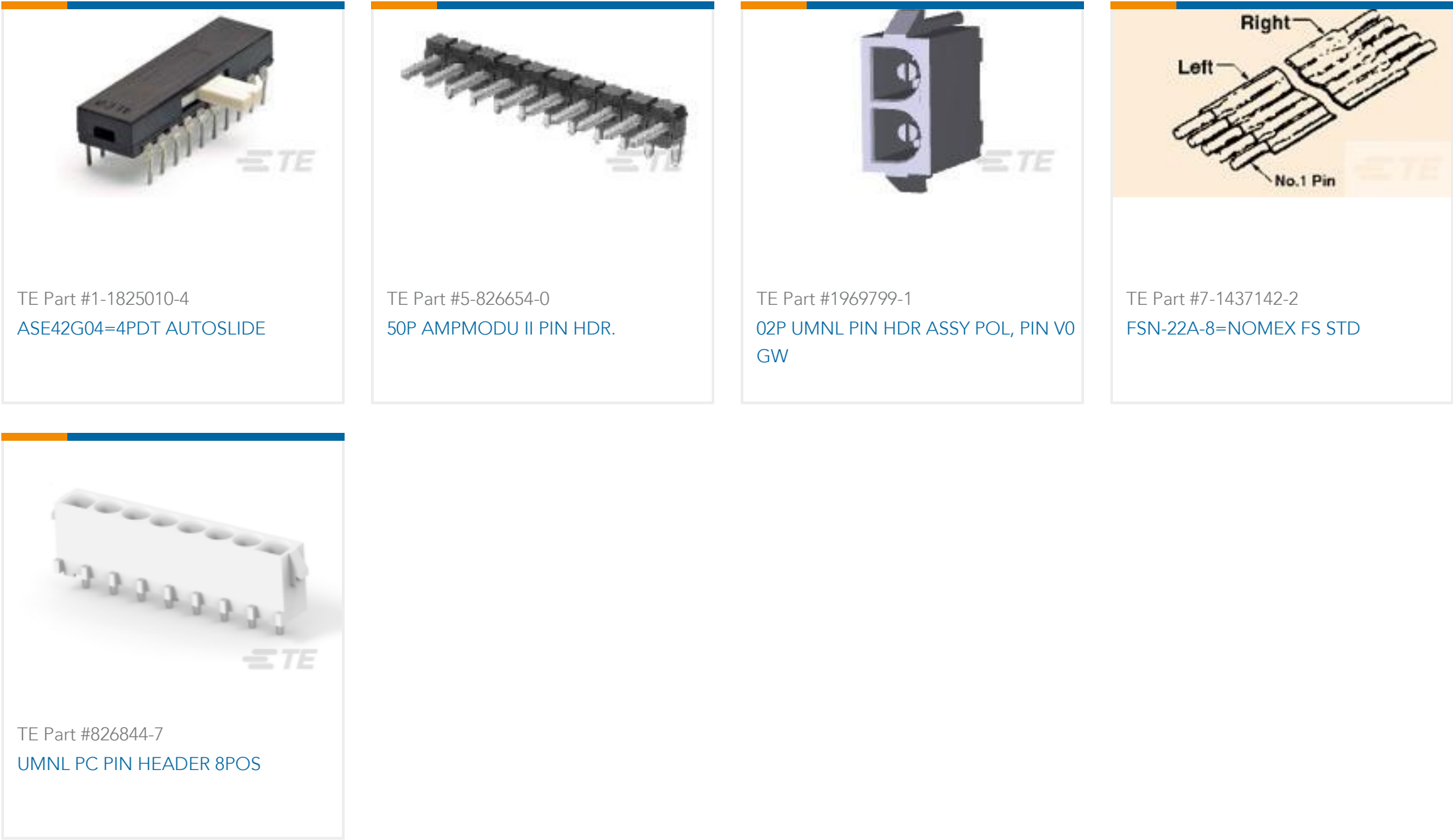


Also in the Series | **DDR3 SO DIMM**



Customers Also Bought





Documents

Product Drawings

EMBOSS ASS'Y DDR SODIMM SOCKET

English

CAD Files

Customer View Model

ENG\_CVM\_CVM\_1717254-1\_D1.2d\_dxf.zip

English

3D PDF

3D

Customer View Model

ENG\_CVM\_CVM\_1717254-1\_D1.3d\_igs.zip

English

Customer View Model

ENG\_CVM\_CVM\_1717254-1\_D1.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Product Specifications

Product Specification

English